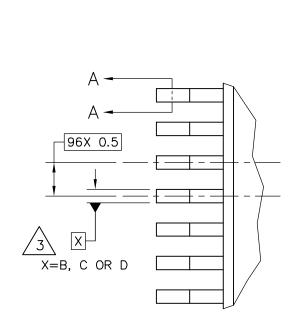
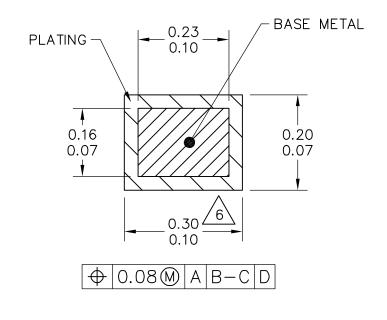
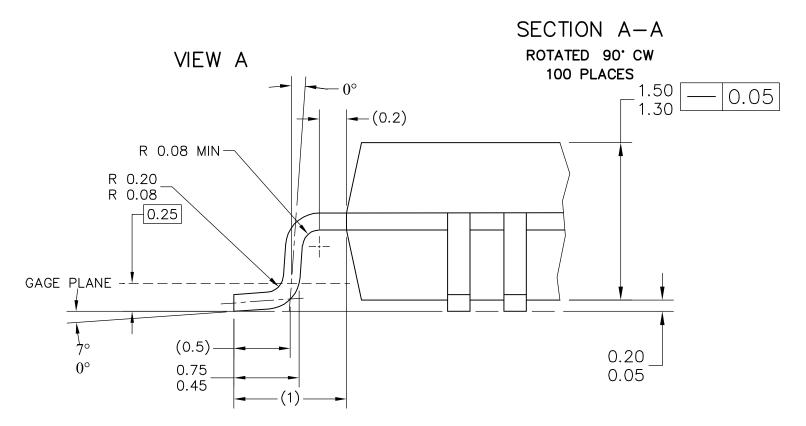


SIDE VIEW

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TITLE:  100 LEAD LQFP  14 X 14, 0.5 PITCH, 1.4 THICK		DOCUMENT NO	): 98ASS23308W	REV: H
		CASE NUMBER	2: 983–02	25 MAY 2005
	1111010	STANDARD: NO	N-JEDEC	







VIEW B

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TITLE:		DOCUMENT NO	): 98ASS23308W	REV: H
100 LEAD LQFP 14 X 14, 0.5 PITCH, 1.4 THI	- THICK	CASE NUMBER	R: 983–02	25 MAY 2005
	1111011	STANDARD: NO	DN-JEDEC	

## NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
- 3. DATUMS B, C AND D TO BE DETERMINED AT DATUM PLANE H.
- 4. THE TOP PACKAGE BODY SIZE MAY BE SMALLER THAN THE BOTTOM PACKAGE SIZE BY A MAXIMUM OF 0.1 mm.
- 5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSIONS. THE MAXIMUM ALLOWABLE PROTRUSION IS 0.25 mm PER SIDE. D1 AND E1 ARE MAXIMUM BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
- 6. DIMENSION 6 DOES NOT INCLUDE DAM BAR PROTRUSION. PROTRUSIONS SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.35. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL BE 0.07 MM.
- 7. DIMENSIONS D AND E ARE DETERMINED AT THE SEATING PLANE, DATUM A.

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		STANDARD: NO	N-JEDEC	